



## Application of Finite Element and Topology Optimization Methods in Smart Structures and Materials

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Deadline for manuscript submissions:

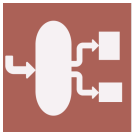
**closed (31 July 2024)**

### Message from the Guest Editors

Tailored and as-designed smart materials have gained popularity and prominence in several applications due to the recent advancements in the fields of additive manufacturing and numerical solvers (finite element, optimization, etc.). This Special Issue, entitled “Application of Finite Element and Topology Optimization Methods in Smart Structures and Materials”, seeks high-quality and original works that focus on (but are not limited to) the following topics:

- Bottom-up, finite element multiscale/multiphysics simulations of architectural and smart materials;
- Top-down inverse design of architectural and smart materials;
- Multiscale and multiphysics topology optimization;
- Multiscale computations based on generalized continuum mechanics (Cosserat, second gradient, etc.).
- Data-driven, reduced-order and machine learning finite elements for multiscale computations and topology optimization solvers.





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## Message from the Editor-in-Chief

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